



Material Content Data Sheet



Sales Product Name		IPS031N03L G		Issued		27. September 2017		
MA#		MA000788524						
Package		PG-TO251-3-311		Weight*		335.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.247	0.67	0.67	6703	6703
leadframe	non noble metal	iron	7439-89-6	0.156	0.05		464	
	inorganic material	phosphorus	7723-14-0	0.047	0.01		139	
	non noble metal	copper	7440-50-8	155.372	46.35	46.41	463519	464122
wire	non noble metal	aluminium	7429-90-5	3.786	1.13	1.13	11294	11294
encapsulation	organic material	carbon black	1333-86-4	0.322	0.10		960	
	plastics	epoxy resin	-	19.423	5.79		57945	
	inorganic material	silicondioxide	60676-86-0	126.515	37.74	43.63	377429	436334
leadfinish	non noble metal	tin	7440-31-5	3.002	0.90	0.90	8954	8954
plating	inorganic material	phosphorus	7723-14-0	0.004	0.00		11	
	non noble metal	nickel	7440-02-0	1.555	0.46	0.46	4638	4649
solder	noble metal	silver	7440-22-4	0.053	0.02		159	
	non noble metal	tin	7440-31-5	0.043	0.01		127	
	non noble metal	lead	7439-92-1	2.035	0.61	0.64	6072	6358
heatspreader	non noble metal	iron	7439-89-6	0.021	0.01		62	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	20.617	6.15	6.16	61506	61586
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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